



## Material Content Data Sheet



<b>Sales Product Name</b>				BSZ110N06NS3 G		<b>Issued</b>		7. January 2016	
<b>MA#</b>				MA000473712					
<b>Package</b>				PG-TSDSON-8-22		<b>Weight*</b>		36.50 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.296	3.55	3.55	35510	35510	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65		
	non noble metal	zinc	7440-66-6	0.009	0.03		259		
	non noble metal	iron	7439-89-6	0.189	0.52		5189		
wire	non noble metal	copper	7440-50-8	7.689	21.07	21.63	210677	216190	
	noble metal	gold	7440-57-5	0.075	0.21	0.21	2054	2054	
	encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		995	
plastics	plastics	epoxy resin	-	1.870	5.12		51245		
	inorganic material	silicondioxide	60676-86-0	16.251	44.52	49.74	445286	497526	
leadfinish	non noble metal	tin	7440-31-5	0.375	1.03	1.03	10267	10267	
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2214	2214	
solder	non noble metal	tin	7440-31-5	0.072	0.20		1974		
	non noble metal	lead	7439-92-1	1.369	3.75	3.95	37510	39484	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32		
	non noble metal	zinc	7440-66-6	0.005	0.01		129		
	non noble metal	iron	7439-89-6	0.094	0.26		2575		
	non noble metal	copper	7440-50-8	3.816	10.46	10.73	104557	107293	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		107		
	non noble metal	iron	7439-89-6	0.078	0.21		2147		
	non noble metal	copper	7440-50-8	3.182	8.72	8.94	87181	89462	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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